

SOT963-1

plastic thin fine-pitch ball grid array package; 44 balls; body
3 x 5 x 0.9 mm

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	TFBGA44
Package type industry code	TFBGA44
Package style descriptive code	TFBGA (thin fine-pitch ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	22-8-2006

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	4.9	-	5	5.1	mm
E	package width	2.9	-	3	3.1	mm
A	seated height	[tbd]	-	1.2	1.2	mm
A ₂	package height	0.85	-	0.9	0.95	mm
n ₂	actual quantity of termination	-	-	44	-	



2. Package outline

TFBGA44: plastic thin fine-pitch ball grid array package; 44 balls; body 3 x 5 x 0.9 mm SOT963-1

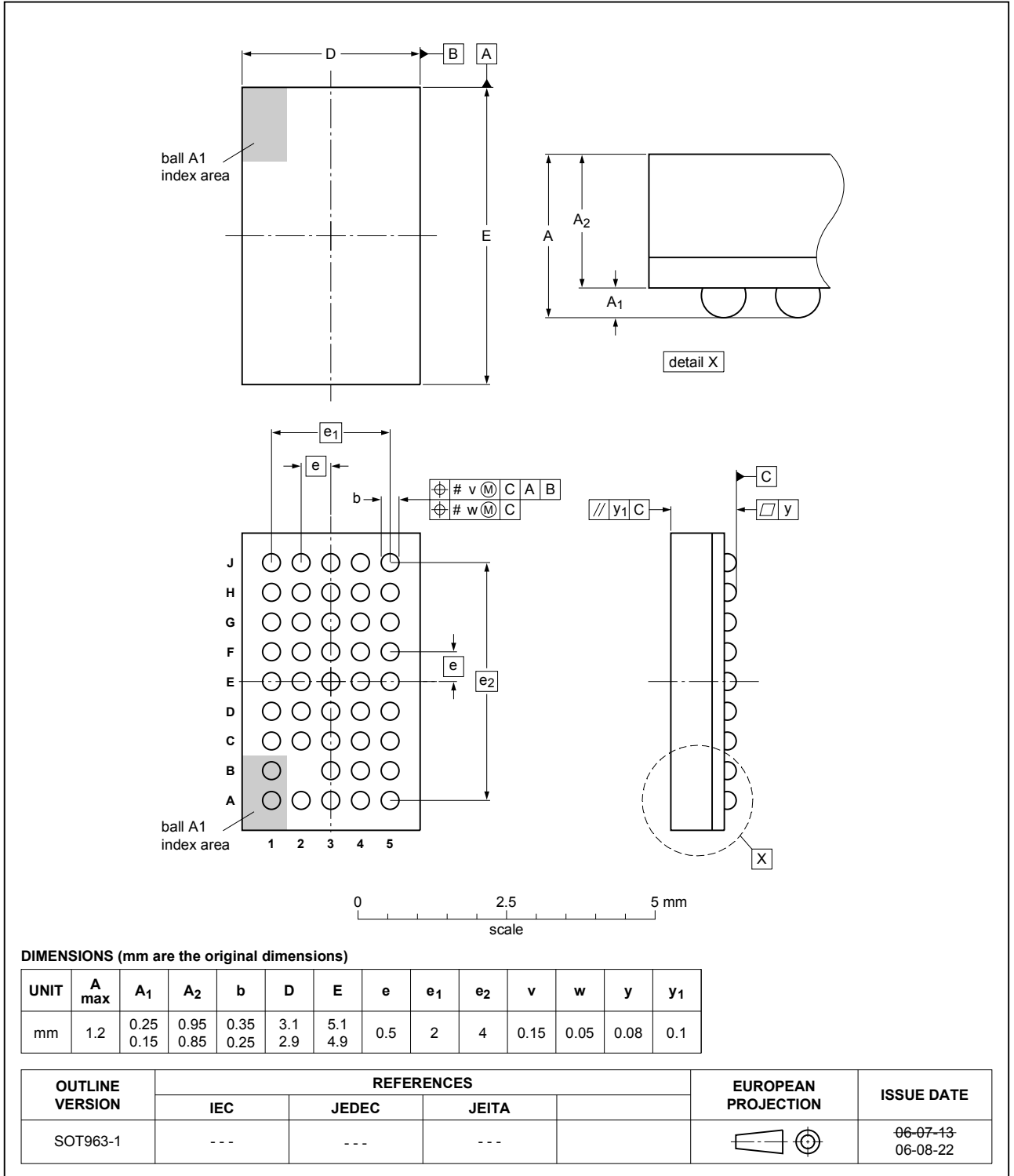


Fig. 1. Package outline TFBGA44 (SOT963-1)

3. Soldering

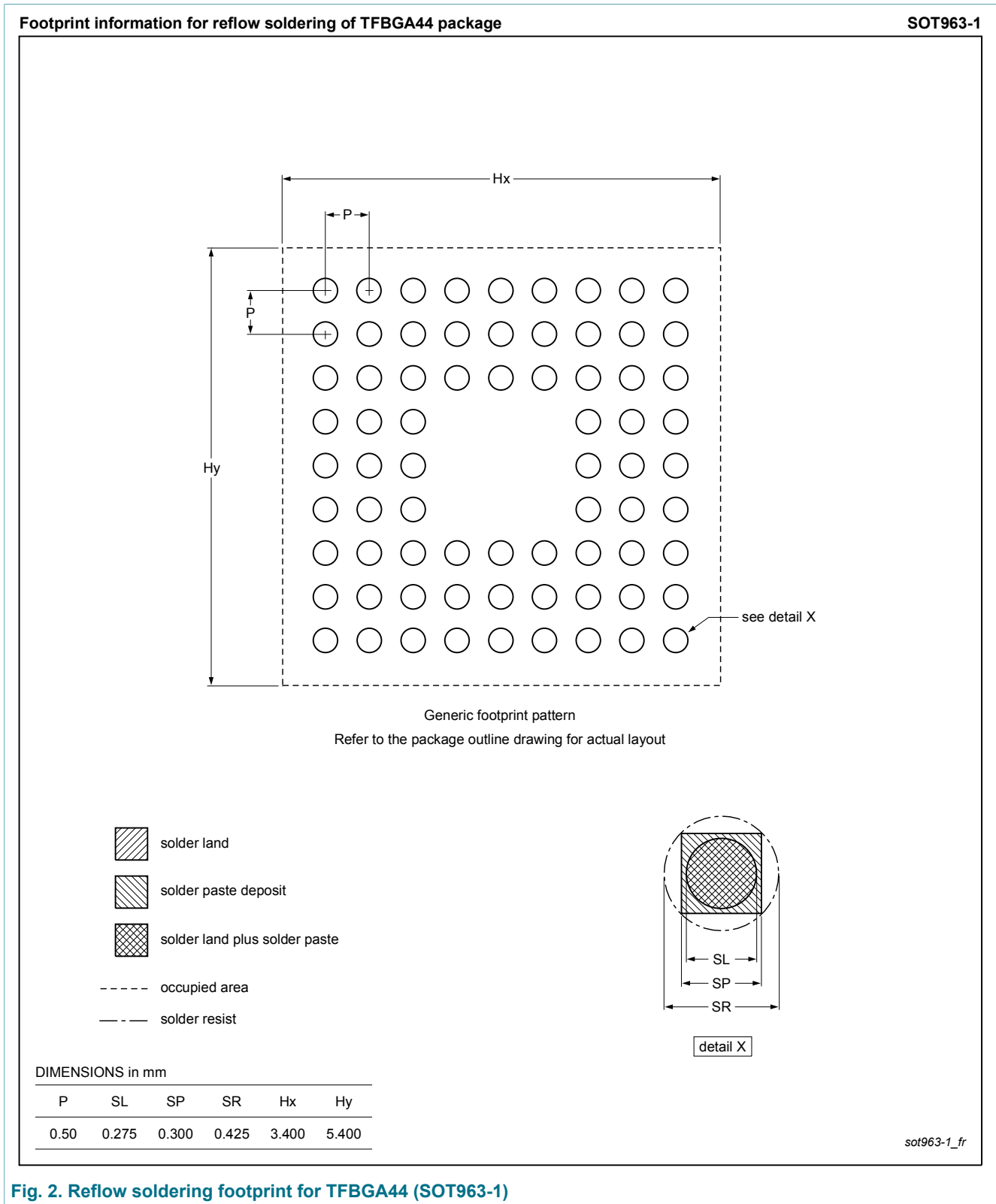


Fig. 2. Reflow soldering footprint for TFBGA44 (SOT963-1)

4. Legal information

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